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2015年3月

FDMC86160ET100

N 沟道屏蔽栅极 Power Trench® MOSFET 100 V, 43 A, 14 mΩ

特性

- T」 额定值扩展: 175°C
- 屏蔽栅极 MOSFET 技术
- 最大 $r_{DS(on)}$ = 14 $m\Omega$ (V_{GS} = 10 V, I_D = 9 A)
- 最大 $r_{DS(on)}$ = 23 m Ω (V_{GS} = 6 V, I_D = 7 A)
- 高性能沟道技术可实现极低的 r_{DS(on)}
- 终端无引线且符合 RoHS 标准

概述

此 N 沟道 MOSFET 采用 Fairchild 带屏蔽栅极技术的先进 PowerTrench® 工艺生产。该工艺针对导通电阻进行了优化。此器件非常适合需要在小空间内实现超低 R_{DS} (on)的应用,例如高 性能 VRM、 POL 和 Orring 功能。

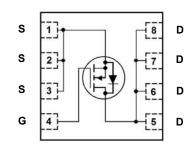
应用

- 桥式拓扑
- 同步整流器





引脚1



MOSFET 最大额定值 T_A = 25 ℃ 除非另有说明

Power 33

顶

符号			参数		额定值	单位
V _{DS}	漏极一源极电压	<u>T</u>			100	V
V_{GS}	栅极一源极电压	<u>E</u>			±20	V
	漏极电流	- 连续	T _C = 25 °C	(注5)	43	
		- 连续	T _C = 100 °C	(注5)	31	A
I _D		- 连续	T _A = 25 °C	(注 1a)	9	^
		- 脉冲		(注4)	204	
E _{AS}	单脉冲雪崩能量	里		(注3)	181	mJ
P _D	功耗		T _C = 25 °C		65	W
	功耗		T _A = 25 °C	(注 1a)	2.8	VV
T _J , T _{STG}	工作和存储结准	量范围			-55 至 +175	°C

热性能

$R_{ heta JC}$	结至外壳热阻	(注 1)	2.3	°C/M
$R_{\theta JA}$	结至环境热阻	(注 1a)	53	C/VV

封装标识与定购信息

器件标识	器件	封装	卷尺寸	带宽	数量
FDMC86160ET	FDMC86160ET100	Power33	13 "	12 mm	3000 个

电气特性 T」= 25°C 除非另有说明

关断特性						
BV_DSS	漏极一源极击穿电压	$I_D = 250 \mu\text{A}, V_{GS} = 0 \text{V}$	100			V
$\frac{\Delta BV_{DSS}}{\Delta T_{J}}$	击穿电压温度系数	I _D = 250 μA, 参考温度为 25 °C		73		mV/°C
I _{DSS}	零栅极电压漏极电流	V _{DS} = 80 V, V _{GS} = 0 V			1	μΑ
I_{GSS}	栅极一源极漏电流	$V_{GS} = \pm 20 \text{ V}, V_{DS} = 0 \text{ V}$			±100	nA

测试条件

导通特性

符号

$V_{GS(th)}$	栅极一源极阈值电压	$V_{GS} = V_{DS}, I_D = 250 \mu A$	2	2.9	4	V
$\frac{\Delta V_{GS(th)}}{\Delta T_J}$	栅极一源极阈值电压温度系数	I _D = 250 μA, 参考温度为 25 °C		-9		mV/°C
r _{DS(on)}		V _{GS} = 10 V, I _D = 9 A		11.2	14	
	漏极至源极静态导通电阻	V _{GS} = 6 V, I _D = 7 A		16	23	mΩ
, ,		$V_{GS} = 10 \text{ V}, I_D = 9 \text{ A}, T_J = 125 °C$		21	26	
9 _{FS}	正向跨导	V _{DD} = 10 V, I _D = 9 A		43		S

动态特性

C _{iss}	输入电容	V - 50 V V - 0 V		968	1290	pF
Coss	输出电容	$V_{DS} = 50 \text{ V}, V_{GS} = 0 \text{ V},$ f = 1 MHz		241	320	pF
C _{rss}	反向传输电容	1 = 1 WH12		11	20	pF
R_a	栅极阻抗		0.1	0.6	2.5	Ω

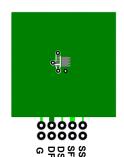
开关特性

t _{d(on)}	导通延迟时间		9.7	19	ns
t _r	上升时间	V _{DD} = 50 V, I _D = 9 A,	3.6	10	ns
t _{d(off)}	关断延迟时间	V_{GS} = 10 V, R_{GEN} = 6 Ω	16	30	ns
t _f	下降时间		3.4	10	ns
$Q_{g(TOT)}$	总栅极电荷	V _{GS} = 0 V 至 10 V	15	22	nC
$Q_{g(TOT)}$	总栅极电荷	V _{GS} = 0 V 至 6 V V _{DD} = 50 V,	9.8	15	nC
Q_{gs}	总栅极电荷	I _D = 9 A	4.4		nC
Q_{gd}	栅极一漏极"米勒"电荷		3.5		nC

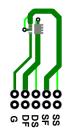
漏极-源极二极管特性

		V _{GS} = 0 V, I _S = 9 A	(注2)	0.79	1.3	V
V_{SD}	VSD I提份一满粉一粉包比回电压	$V_{GS} = 0 \text{ V}, I_{S} = 1.9 \text{ A}$	(注 2)	0.72	1.2	V
t _{rr}	反向恢复时间			47	75	ns
Q _{rr}	反向恢复电荷	$I_F = 9 \text{ A, di/dt} = 100 \text{ A/}\mu\text{s}$		45	73	nC

注意: 1. R_{BJA} 取决于安装在一平方英寸衬垫, 2 oz 铜焊盘以及 FR-4 材质尺寸 1.5 x 1.5in. 的衬垫上的器件。 R_{BCA} 由用户的电路板设计确定。



53 安装在 2 oz 最小 1 in² 铜 a.焊盘上时的 °C/W



125 安装在 2 oz 最小铜焊盘上 b.时的 °C/W

最小值 典型值 最大值 单位

- 2. 脉冲测试:脉冲宽度:<300 μs,占空比:< 2.0%。
- $3.~E_{AS}$ 为 181~mJ,根据起始 T_{J} = $25~^{\circ}C$ 、 L = 3~mH 、 I_{AS} = 11~A 、 V_{DD} = 100~V 、 V_{GS} = 10~V 。 在 L = 0.1~mH 、 I_{AS} = 35~A 时进行 100% 测试。
- 4. 有关脉冲编号的更多详情,请参考图 11 中的 SOA 图形。
- 5. 计算得到的连续电流仅限于最大结温,实际连续电流将受限于散热以及电气机械应用的电路板设计。

典型特性 T」= 25℃ 除非另有说明

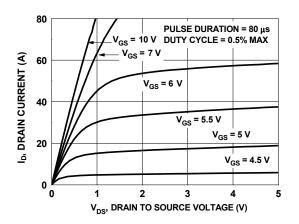


图 1. 通态区域特性

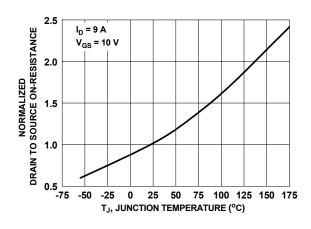


图 3. 标准化导通电阻与结温的关系

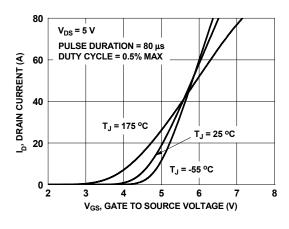


图 5. 转换特性

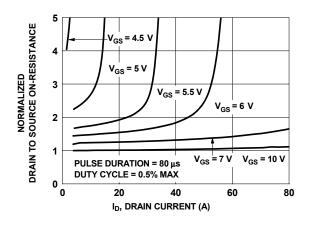


图 2. 标准化导通电阻与漏极电流和栅极电压的关系

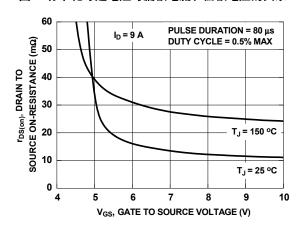


图 4. 导通电阻与栅极 - 源极电压的关系

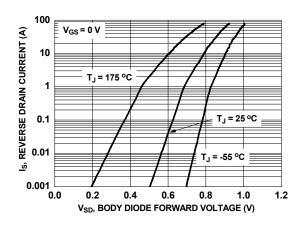


图 6. 源极 - 漏极二极管正向电压与源电流的关系

典型特性 T」 = 25°C 除非另有说明

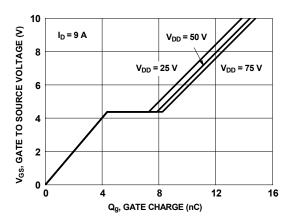


图 7. 栅极电荷特性

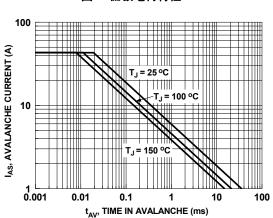


图 9. 非箝位电感开关能力

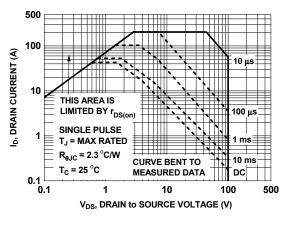


图 11. 正向偏压安全工作区

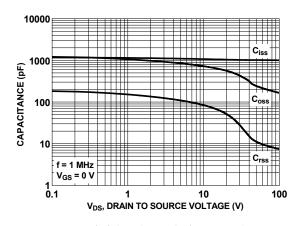


图 8. 电容与漏极 - 源极电压的关系

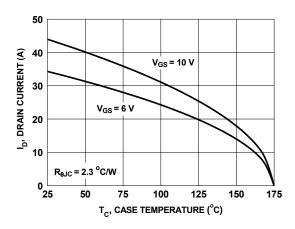


图 10. 最大连续漏极电流与壳温的关系

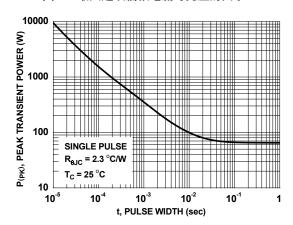


图 12. 单个脉冲最大功耗

典型特性 T」= 25℃ 除非另有说明

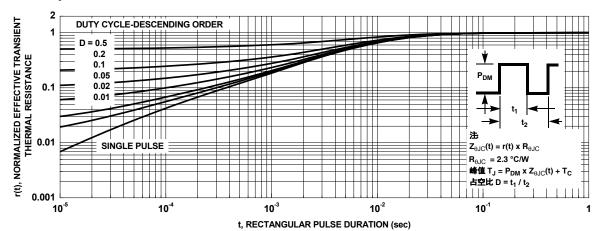
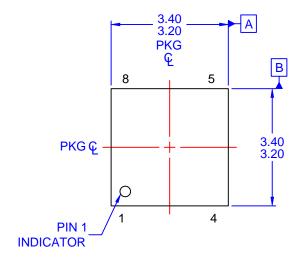
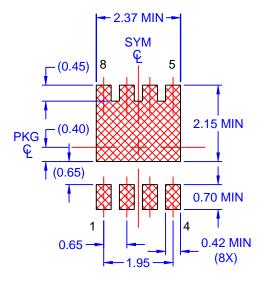


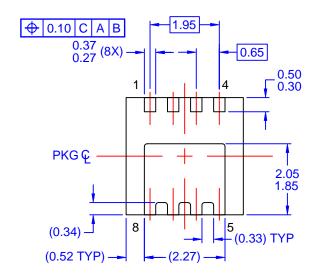
图 13. 结至外壳瞬态热响应曲线





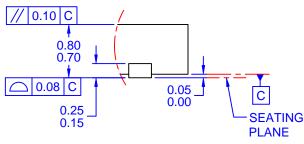


LAND PATTERN RECOMMENDATION



NOTES: UNLESS OTHERWISE SPECIFIED

- A) PACKAGE STANDARD REFERENCE: JEDEC MO-240, ISSUE A, VAR. BA, DATED OCTOBER 2002.
- B) ALL DIMENSIONS ARE IN MILLIMETERS.
- C) DIMENSIONS DO NOT INCLUDE BURRS OR MOLD FLASH. MOLD FLASH OR BURRS DOES NOT EXCEED 0.10MM.
- D) DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
- E) DRAWING FILE NAME: PQFN08HREV1



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